ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	vithin the manufact level materials for	urer listed which the	item. Note manufactur	: if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute					rials and Mfg Information					
upplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2023-0	2023-06-08			
Contact Name Title - Conta			Contact			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product E			ct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Rep			Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product En			act Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Effective Date Version Mar		Ianufacturing Site	nufacturing Site		UOM	Unit Type	
	MC74A	MC74AC11DG LOG C		LOG CMOS GATE AND TRPL		2023-06-08		P	PH1		122.05	mg	Each	
Ianufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial 7	Ferminal Base	Iloy J-STD-020 MSL Ratin		L Rating	Peak Proce	Peak Process Body Temperat		ure Max Time at Peak Temp		ature Nun	nber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU A		CU Alloy	1			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperatu	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl bhthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg
			Supplier	Epoxy resins	129915-35-1		1.11	mg
Lead Frame	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0835	mg
			Supplier	Iron (Fe)	7439-89-6		1.6361	mg
			Supplier	Copper (Cu)	7440-50-8		67.1137	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0209	mg
Mold Compound-Black	43.43	mg		Epoxy Phenol Resin	proprietary data		4.5601	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.8699	mg
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg